

1752-2 1.1

## Material Composition Declaration

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ICP Web Site for information on IPC-1752 Standard  
<http://www.ipc.org/IPC-175x>

Form Type\*  
Distribute

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

**Declaration Class\***  
**Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg**  
**Information**

### Supplier Information

Company Name *	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	Response Date* Sat, Aug 31, 2013 03:43 AM
Contact Name *	Title - Contact Product Ecology	Phone - Contact * <b>801-562-7455</b>	Email - Contact * <b>david.lancaster@fairchildsemi.com</b>
Authorized Representative *	Title - Representative Product Ecology	Phone - Representative * <b>801-562-7455</b>	Email - Representative * <b>david.lancaster@fairchildsemi.com</b>

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
MMBT2222AT	MMBT2222AT	SOT-523F-3 (G)			SUBCONTRACTOR	<b>0.002606</b>	g	Each

### Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	CU Alloy	1	260 C	30 seconds	3

\* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
<b>RoHS Directive 2011/65/EU</b>	<b>RoHS Definition:</b> Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
<p>This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.</p> <p>The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.</p> <p>Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the minuscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.</p>		
<b>RoHS Declaration *</b>	<b>1 - Item(s) does not contain RoHS restricted substances per the definition above</b>	<b>Supplier Acceptance * Accepted</b>
<p><b>Exemptions:</b> If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.</p> <p>Exemption List Version EL-2011/534/EU None</p>		

#### Declaration Signature

Supplier Signature	
DAVID LANCASTER - PRODUCT ECOLOGY MANAGER	

**Homogeneous Material Composition Declaration for Electronic Products**

Item/SubItem Name SOT-523F-3 (G)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	0.070	Supplier		Silicon	0.070	7440-21-3	26859
Encapsulation	Thermoplastics	1.535	Supplier		Carbon Black	0.008	1333-86-4	2935
			Supplier		Epoxy Resin	0.383	29690-82-2	146958
			Supplier		Silica, vitreous	1.140	60676-86-0	437420
Lead Frame	Copper & its alloys	0.926	Supplier		Copper	0.878	7440-50-8	336890
			B	Nickel (external applications only)	Nickel	0.029	7440-02-0	11012
			Supplier		Silver	0.011	7440-22-4	4297
			Supplier		Tin	0.008	7440-31-5	2931
Plating	Other Nonferrous metals & alloys	0.070	Supplier		Tin	0.070	7440-31-5	26859
Wire Bond	Precious metals	0.010	Supplier		Gold	0.010	7440-57-5	3837